

# Bill of Materials

TI DESIGNS

ITEM	QTY	REFERENCE DESIGNATOR	VALUE	DESCRIPTION	SIZE	MANUFACTURER	MANUFACTURER PART NUMBER
1	13	C1,C4,C6,C7,C10,C16,C17, C19,C20,C21,C22,C24,C30	0.1uF	CAP CERAMIC .1UF 25V X5R 0402	CAP_0402	TDK	C1005X5R1E104K050BC
2	3	C2,C5,C8	4.7uF	CAP CERAMIC 4.7UF 10V X5R 0603	CAP_0603	TDK	CGB3B1X5R1A475K055AC
3	2	C3,C9	0.01uF	CAP CERAMIC .01UF 25V X5R 0402	CAP_0402	TDK	C1005X7R1E103K050BB
4	2	C11,C33	22uF	CAP CERAMIC 22UF 6.3V X5R 0603	CAP_0603	TDK	C1608X5R0J226M080AC
5	2	C12,C13	1uF	CAP CERAMIC 1UF 10V X5R 0603	CAP_0603	TDK	C1608X5R1A105K080AC
6	2	C14,C28	1000pF	CAP CERAMIC .001UF 50V X7R 0402	CAP_0402	TDK	C1005X7R1H102K050BA
7	2	C15,C18	10uF	CAP CERAMIC 10UF 10V X5R 0603	CAP_0603	TDK	C1608X5R1A106K080AC
8	2	C23,C26	1000pF, DNI	CAP CERAMIC .001UF 50V X7R 0402	CAP_0402	TDK	C1005X7R1H102K050BA
9	2	C25,C29	100pF	CAP CER 100PF 50V 5% NP0 0402	CAP_0402	TDK	C1005C0G1H101J050BA
10	1	C27	10 uF	CAP CER 10UF 25V 20% X7R 1210	CAP_1210	TDK	C3225X7R1E106M
11	2	C31,C32	18pF	CAP CER 18PF 50V 5% NP0 0402	CAP_0402	TDK	C1005C0G1H180J050BA
12	1	D1	J23TE2-66C-R02M-2.6	InGaAs Detector	9Pin_Socket	Teledyne Judson	J23TE2-66C-R02M-2.6
13	1	J1	S4B-EH	CONN HEADER EH SIDE 4POS 2.5MM	CON_JST_4PIN	JST	S4B-EH(LF)(SN)
14	1	J2	874381043	CONN HEADER 10POS 1.5MM R/A SMD	CONN_10_RA_SMT	Molex	874381043
15	1	R1	10K	RES 10K OHM 1/16W 1% 0402 SMD	RES_0402	Yageo	RC0402FR-0710KL
16	2	R2,R18	24K	RES 24K OHM 1/16W 1% 0402 SMD	RES_0402	Yageo	RC0402FR-0724KL
17	4	R3,R4,R5,R9	100K	RES 100K OHM 1/16W 1% 0402 SMD	RES_0402	Yageo	RC0402FR-07100KL
18	3	R6,R7,R8	100K, DNI	RES 100K OHM 1/16W 1% 0402 SMD	RES_0402	Yageo	RC0402FR-07100KL
19	2	R10,R17	301	RES 301 OHM 1/16W 1% 0402 SMD	RES_0402	ROHM	RC0402FR-07301RL
20	3	R11,R12,R13	100	RES 100 OHM 1/16W 1% 0402 SMD	RES_0402	ROHM	MCR01MRTF1000
21	3	R14,R15,R16	0, DNI	RES 0.0 OHM 1/8W JUMP 0805 SMD	RES_0805	Yageo	RC0805JR-070RL
22	1	R19	49.9	RES 49.9 OHM 1/16W 1% 0402 SMD	RES_0402	ROHM	MCR01MRTF49R9
23	1	U1	TPS71733DCK	IC REG LDO 3.3V 0.15A SC70-5	SC70-5	Texas Instruments	TPS71733DCK
24	1	U2	UA78L06ACPK	IC REG LDO 6.2V 0.1A SOT89-3	SOT89-3	Texas Instruments	UA78L06ACPK
25	1	U3	TPS71750DSE	IC REG LDO 5V 0.15A 6WSON	6WSON	Texas Instruments	TPS71750DSE
26	1	U4	REF5025AIDGK	IC VREF SERIES PREC 2.5V 8VSSOP	8VSSOP	Texas Instruments	REF5025AIDGK
27	1	U5	OPA350EA	IC OPAMP GP 38MHZ RRO 8VSSOP	8VSSOP	Texas Instruments	OPA350EA
28	1	U6	OPA2376AID	IC OPAMP GP 5.5MHZ DUAL LN 8SOIC	SO8	Texas Instruments	OPA2376AID
29	1	U7	ADS1255IDB	IC ADC 24-BIT SPI PROGBL 20-SSOP	SSOP_20	Texas Instruments	ADS1255IDB
30	1	Y1	7.68MHz	CRYSTAL 7.68MHZ 18PF SMD	CRYSTAL_HCM49	Citizen	HCM49-7.680MABJ-UT
31	9	D1; Pins 1 -> 9		CONN RECEIPT PIN .110" .025"		Mill-Max	0300-1-15-15-47-27-10-0
32	1	D1; Pin 10		PC PIN .040 DIA031102-2 SERIES		Mill-Max	3102-2-00-21-00-00-08-0

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